

GBU2006 THRU GBU2010

General Bridge Rectifiers



Voltage: 600~1000 Volts

Current: 20.0 Amperes

Package: GBU

Features

- NH'S Standard Rectifier Chip Technology
- Low Forward Voltage Drop For High Efficiency
- Low Leakage Current For High Reliability
- High Surge Capability For High Reliability

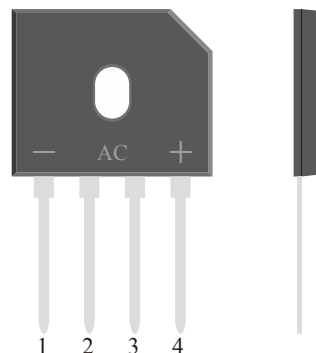
Mechanical Data

- **Case:** Molded With UL-94 Class V-0 Recognized, RoHS-Compliant
- **Polarity:** Look At The Diagram And Polarity On The Right
- **Terminals:** Tin Plated Leads, Solderable Per J-STD-002 And JESD22-B102

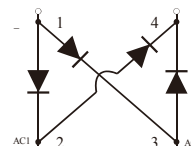
Typical Applications

- Switch Mode Power Supplies (SMPS)
- Fast Chargers
- LED Driver And Monitor Lighting
- Automotive Electronics And Charging Posts

Diagram:



Polarity:



Single Phase, Half Wave, 60Hz, Resistive Or Inductive Load. For Capacitive Load, Derate Current By 20%

Maximum Ratings (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	GBU 2006	GBU 2008	GBU 2010	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	600	800	1000	V
Maximum RMS Voltage		V_{RMS}	420	560	700	V
Maximum DC Blocking Voltage		V_{DC}	600	800	1000	V
Maximum Average Forward Rectified Current	With Heatsink 100 °C Without Heatsink 25 °C	$I_{F(AV)}$	20 3.6			A
Peak Forward Surge Current Per Diode	8.3ms Single Half Sine-wave Superimposed On Rate Load	I_{FSM}	260			A
Current Squared Time Per Diode	$t < 8.3ms$	I^2t	280.5			A ² sec
Maximum Mounting Torque	M3 screw	T_{MM}	1.1			N.m

Electrical Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	GBU 2006	GBU 2008	GBU 2010	Unit
Instantaneous Forward Voltage Per Diode	$I_F = 10.0 A$	V_F	1.0			V
Maximum DC Reverse Current at Rated DC Blocking Voltage	Ta=25°C, $V_R = V_{RRM}$ Ta=125°C, $V_R = V_{RRM} * 80\%$	I_{RRM}	5 500			uA
Typical Junction Capacitance Per Diode	4 V, 1MHz	C_J	85			pF

Thermal Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	GBU 2006	GBU 2008	GBU 2010	Unit
Operating Junction Temperature Range		T _J	-55~150			℃
Storage Temperature Range		T _{STD}	-55~150			
Thermal Resistance Junction To Ambient With Steady-State	Still Air Environment With Ta=25℃	R _{θJA}	22.0			℃/W
Thermal Resistance Junction-Case With Steady-State	Device Mounted On 75mm x 45mm x 2.5mm Alu. Heat.	R _{θJC}	2.2			

Notes: 1. Pulse Test: 300 Us Pulse Width, 1% Duty Cycle

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Typical Characteristics Curves

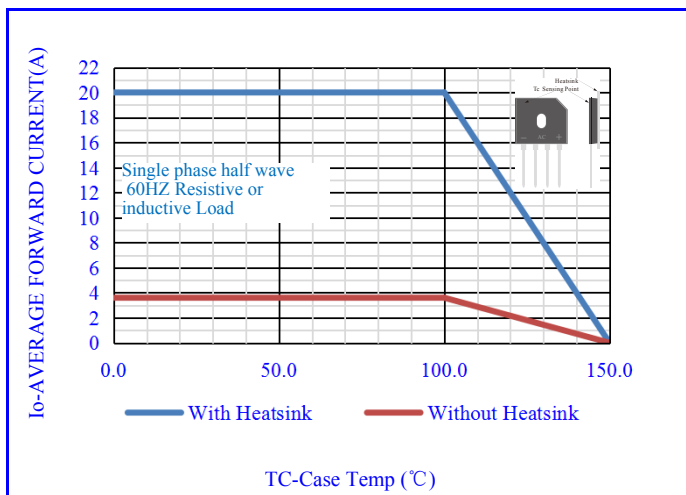


Fig.1-FORWARD CURRENT DERATING CURVE

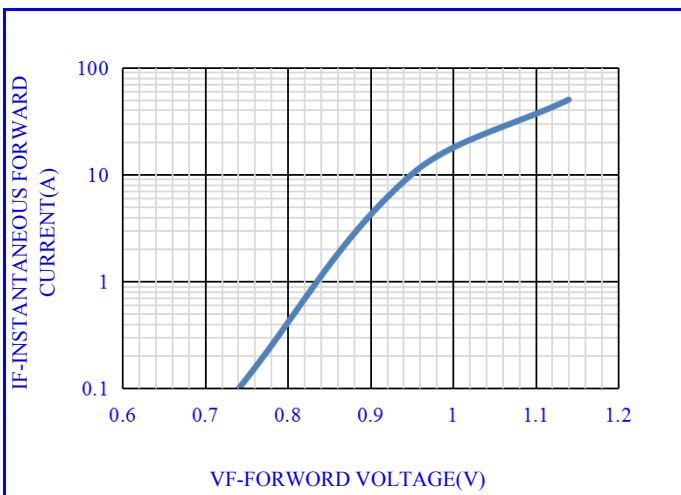


Fig.2- TYPICAL INSTANTANEOUS FORWARD

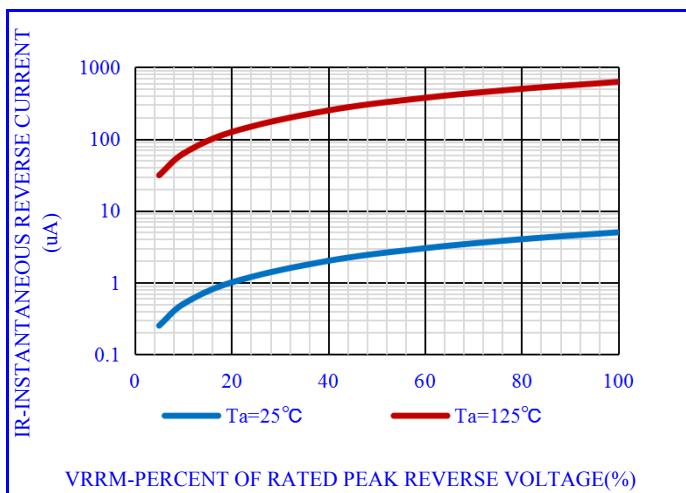


Fig.3- TYPICAL REVERSE CHARACTERISTICS

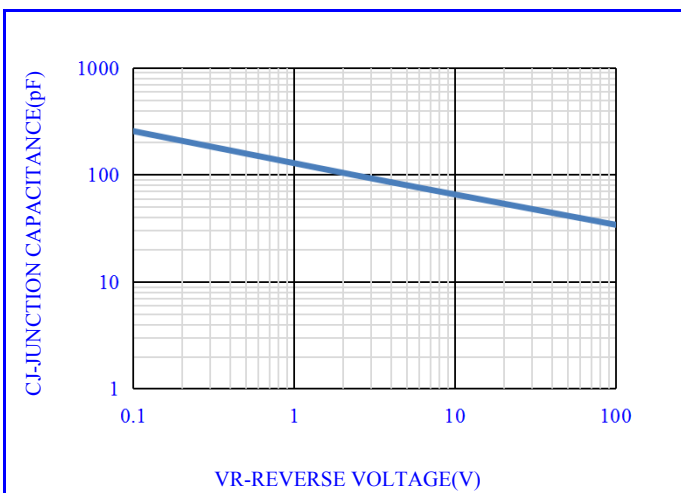


Fig.4- TYPICAL JUNCTION CAPACITANCE

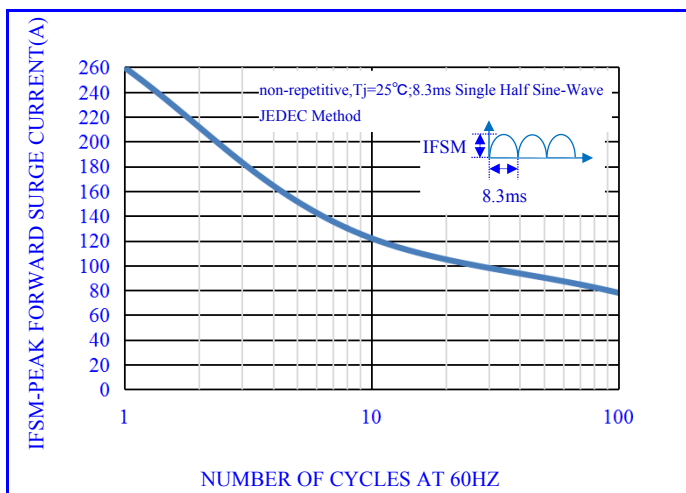


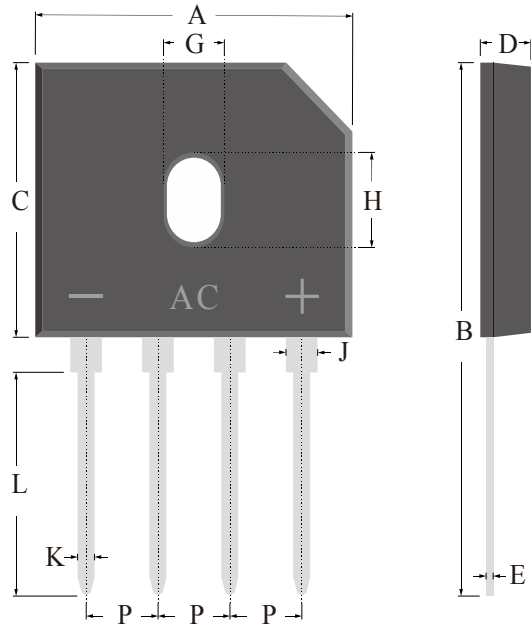
Fig.5-MAX. NON-REPETITIVE SURGE CURRENT

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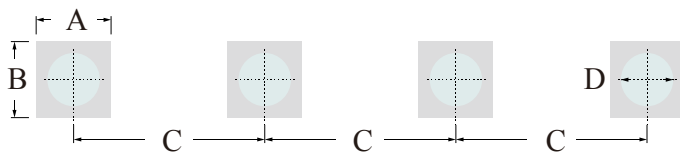
OUTLINE DRAWINGS



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OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	21.00	-	23.00	0.8268	-	0.9055
B	35.35	-	37.35	1.3917	-	1.4705
C	17.50	-	19.50	0.6890	-	0.7677
D	3.15	-	3.75	0.1240	-	0.1476
E	0.35	-	0.65	0.0138	-	0.0256
L	14.50	-	16.50	0.5709	-	0.6496
G	3.40	-	4.00	0.1339	-	0.1575
H	5.40	-	6.00	0.2126	-	0.2362
J	2.00	-	2.50	0.0787	-	0.0984
K	1.00	-	1.40	0.0394	-	0.0551
P	4.80	-	5.40	0.1890	-	0.2126

RECOMMEDND LAYOUT DRAWINGS



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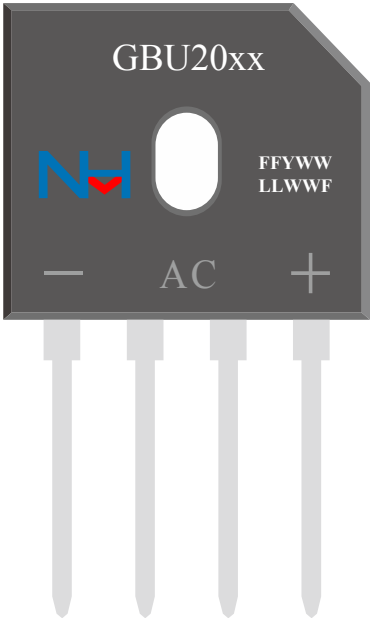
OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	2.00	-	-	0.0787	-
B	-	2.00	-	-	0.0787	-
C	-	5.10	-	-	0.2008	-
D	-	1.40	-	-	0.0551	-

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MARKING



MARKING INSTRUCTION

NH=Niuhang Trademark
FF=Product Line Code,According To Actual Changes
YYWW=Date Code,According To Actual Changes
LLWWF=Inernal Code,According To Actual Changes
GBU20xx=Model,xx=06,08,10

PACKING INFORMATION

Package Type	Package Code	Product Weight Approx(g/Pcs)	Package Method	Quantity (Pcs/Min. Pack.)	Quantity (Pcs/Inner Box)	Quantity (Pcs/Carton)
GBU	P1	3.748	Box	250	250	5000
GBU	P2	3.748	Tube	20	1000	2000

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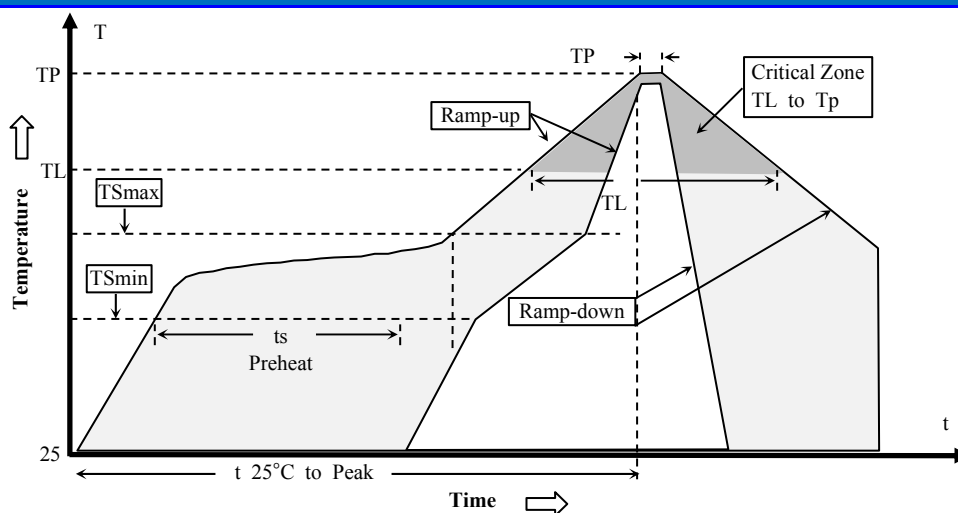
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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(TS min) -Temperature Max(TS max) -Time(ts min to ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (TL) - Time (tL)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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